PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	RESUBMISSION
NATURE OF CONVEYANCE:	ASSIGNMENT
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CONVEYING PARTY DATA

Name	Execution Date
BYUNG WOO KANG	03/29/2021
BON SEOK KOO	03/29/2021
JEONG RYEOL KIM	03/29/2021
JUNG MIN KIM	03/29/2021
JAE SEOK YI	03/29/2021
JI HYE HAN	03/29/2021
HYE JIN PARK	03/29/2021

RECEIVING PARTY DATA

Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.
Street Address:	MAEYOUNG-RO 150 (MAETAN-DONG), YOUNGTONG-GU
City:	SUWON-SI, GYEONGGI-DO
State/Country:	KOREA, REPUBLIC OF

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	18198419

CORRESPONDENCE DATA

Fax Number: (202)739-3001

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2027393000
Email: patents@morganlewis.com, christine.peoples@morganlewis.com
Correspondent Name: HOSANG LEE
Address Line 1: MORGAN, LEWIS & BOCKIUS LLP
Address Line 2: 1111 PENNSYLVANIA AVENUE NW
Address Line 4: WASHINGTON, D.C. 20004

ATTORNEY DOCKET NUMBER:	123193-9048-US
NAME OF SUBMITTER:	CHRISTINE PEOPLES
SIGNATURE:	/Christine Peoples/
DATE SIGNED:	07/26/2023

Total Attachments: 3
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COMBINED DECLARATION (37 CFR 1.63) FOR U.S. PATENT APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT OF INVENTION

Title of Invention	MULTILAYER ELECTRONIC COMPONENT

DECLARATION

As the below named and undersigned inventor, I hereby declare that:

This declaration is directed to:	X	The attached application, or
	☐	United States application or PCT international application number ____________ filed on ____________

The above-identified application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Note to Inventor: 37 C.F.R. § 1.63(c) states: *A person may not execute an oath or declaration for an application unless that person has reviewed and understands the contents of the application, including the claims, and is aware of the duty to disclose to the Office all information known to the person to be material to patentability as defined in § 1.56.*

ASSIGNMENT

WHEREAS, I have made an invention described and/or claimed in the above-identified application; and
WHEREAS, **SAMSUNG ELECTRO-MECHANICS CO., LTD.** a corporation of the Republic of Korea, having a place of business at **Maeyoung-Ro 150 (Maetan-Dong), Youngtong-Gu, Suwon-Si, Gyeonggi-Do, Republic of Korea** , (hereinafter referred to as "ASSIGNEE") desires to acquire the entire right, title, and interest in and to said invention in all countries throughout the world and the above-identified United States patent application;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I have assigned and do hereby assign to the ASSIGNEE, and its lawful successors and assigns, the entire right, title, and interest in and to said invention, the above-identified United States patent application and all divisions, continuations, and continuations-in-part of said application, and reissues, extensions, and renewals of Letters Patent granted thereon, and all corresponding patent applications filed in countries foreign to the United States ("foreign countries") and corresponding international patent applications, and all Letters Patents issuing on any such patent applications in the United States and foreign countries;

I hereby assign to the ASSIGNEE, and its lawful successors and assigns, the right to file patent applications in foreign countries on said invention in its own name and the right to claim priority to the above-identified United States patent application under the terms of the International Convention and any other relevant treaties;

I hereby authorize and request the United States Patent and Trademark Office and officials in patent offices in foreign countries to issue any and all of said Letters Patent to the ASSIGNEE as the assignee of my entire right, title, and interest in and to the same, for the sole use and benefit of the ASSIGNEE, and its lawful successors and assigns, to the full end of the term for which said Letters Patent may be granted;

I hereby grant the attorney of record the power to insert on this Assignment any further identification that may be necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office or other authority for recordation of this document;

I hereby covenant that I have the full right to convey the interest assigned by this Assignment, and I have not executed and will not execute any agreement in conflict with this Assignment; and

Further, I hereby further covenant and agree that I will, without further consideration, communicate with the ASSIGNEE, and its lawful successors and assigns, any facts known to me respecting this invention, and testify in any legal proceeding, sign all lawful papers when called upon to do so, execute and deliver any and all papers that may be necessary or desirable to perfect the title to this invention in said ASSIGNEE, and its lawful successors or assigns, execute all divisional, continuation, continuation-in-part, and reissue applications, make all rightful oaths and generally do everything possible to aid the ASSIGNEE, and its lawful successors and assigns, to obtain and enforce proper patent protection for this invention in the United States and any foreign country, it being understood that any expense incident to the execution of such papers shall be borne by the ASSIGNEE, and its lawful successors and assigns.

IN TESTIMONY WHEREOF, I have hereunto set my hands.

NAME OF INVENTOR (Full Legal Name) : Byung Woo KANG

Signature: 강 병 우 Date: 2021.03.29

NAME OF INVENTOR (Full Legal Name) : Bon Seok KOO

Signature: 구 본석 Date: 2021.03.29

NAME OF INVENTOR (Full Legal Name) : Jeong Ryeol KIM

Signature: Jeong Ryeol Kim Date: 2021.03.29

NAME OF INVENTOR (Full Legal Name) : Jung Min KIM

Signature: Kim - Jungmin Date: 2021.03.29

NAME OF INVENTOR (Full Legal Name) : Jae Seok YI

Signature: 이재석 Date: 2021.03.29

NAME OF INVENTOR (Full Legal Name) : Ji Hye HAN

Signature: Date: 2021.03.29

NAME OF INVENTOR (Full Legal Name) : Hye Jin PARK

Signature: 박혜진 Date: 2021.03.29